

V_{DRM} = 2800 V
 $I_{T(AV)M}$ = 3760 A
 $I_{T(RMS)}$ = 5900 A
 I_{TSM} = $65.5 \cdot 10^3$ A
 V_{TO} = 0.929 V
 r_T = 0.100 mΩ

Phase Control Thyristor

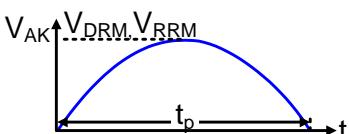
5STP 33L2800

Doc. No. 5SYA1011-07 May. 20

- Patented free-floating silicon technology
 - Low on-state and switching losses
 - Designed for traction, energy and industrial applications
 - Optimum power handling capability
- Interdigitated amplifying gate

Blocking

Maximum rated values¹⁾

Parameter	Symbol	Conditions	5STP 33L2800		Unit
Max repetitive peak forward and reverse blocking voltage	V_{DRM} , V_{RRM}	$f = 50$ Hz, $t_p = 10$ ms, $T_{vj} = 5 \dots 125$ °C, Note 1 	2800		V
Critical rate of rise of commutating voltage	dv/dt_{crit}	Exp. to $0.67 \cdot V_{DRM}$, $T_{vj} = 125$ °C	1000		V/μs

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Forward leakage current	I_{DRM}	V_{DRM} , $T_{vj} = 125$ °C			400	mA
Reverse leakage current	I_{RRM}	V_{RRM} , $T_{vj} = 125$ °C			400	mA

Note 1: Voltage de-rating factor of 0.11% per °C is applicable for T_{vj} below +5 °C.

Mechanical data

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Mounting force	F_M		63	70	84	kN
Acceleration	a	Device unclamped			50	m/s ²
Acceleration	a	Device clamped			100	m/s ²

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Weight	m				1.45	kg
Housing thickness	H	$F_M = 70$ kN, $T_a = 25$ °C	25.95		26.60	mm
Surface creepage distance	D _s		36			mm
Air strike distance	D _a		15			mm

1) Maximum rated values indicate limits beyond which damage to the device may occur

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On-state**Maximum rated values¹⁾**

Parameter	Symbol	Conditions	min	typ	max	Unit
Average on-state current	$I_{T(AV)M}$	Half sine wave, $T_c = 70^\circ C$			3760	A
RMS on-state current	$I_{T(RMS)}$				5900	A
Peak non-repetitive surge current	I_{TSM}	$t_p = 10 \text{ ms}, T_{vj} = 125^\circ C$, sine half wave,			$65.5 \cdot 10^3$	A
Limiting load integral	I^2t	$V_D = V_R = 0 \text{ V}$, after surge			$21.5 \cdot 10^6$	A^2s
Peak non-repetitive surge current	I_{TSM}	$t_p = 10 \text{ ms}, T_{vj} = 125^\circ C$, sine half wave,			$49.5 \cdot 10^3$	A
Limiting load integral	I^2t	$V_R = 0.6 \cdot V_{RRM}$, after surge			$12.3 \cdot 10^6$	A^2s

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
On-state voltage	V_T	$I_T = 3000 \text{ A}, T_{vj} = 125^\circ C$		1.10	1.23	V
Threshold voltage	$V_{(TO)}$				0.929	V
Slope resistance	r_T	$I_T = 2000 \text{ A} - 6000 \text{ A}, T_{vj} = 125^\circ C$			0.100	$\text{m}\Omega$
Holding current	I_H	$T_{vj} = 25^\circ C$			100	mA
		$T_{vj} = 125^\circ C$			60	mA
Latching current	I_L	$T_{vj} = 25^\circ C$			500	mA
		$T_{vj} = 125^\circ C$			300	mA

Switching**Maximum rated values¹⁾**

Parameter	Symbol	Conditions	min	typ	max	Unit	
Critical rate of rise of on-state current	di/dt_{crit}	$T_{vj} = 125^\circ C, I_T = 4000 \text{ A},$ $V_D \leq 0.67 \cdot V_{RRM},$ $I_{GM} = 2 \text{ A}, t_r = 0.5 \mu\text{s}$	Cont. $f = 50 \text{ Hz}$			250	$\text{A}/\mu\text{s}$
			Cont. $f = 1 \text{ Hz}$			1000	$\text{A}/\mu\text{s}$
Circuit-commutated turn-off time	t_q	$T_{vj} = 125^\circ C, I_T = 2000 \text{ A},$ $V_R = 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu\text{s},$ $V_D \leq 0.67 \cdot V_{RRM}, dv_D/dt = 20 \text{ V}/\mu\text{s}$			400	μs	

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Reverse recovery charge	Q_{rr}	$T_{vj} = 125^\circ C, I_T = 2000 \text{ A},$	1000	1870	2200	μAs
Reverse recovery current	I_{RM}	$V_R = 200 \text{ V}, di_T/dt = -1.5 \text{ A}/\mu\text{s}$	35	50	55	A
Gate turn-on delay time	t_{gd}	$T_{vj} = 25^\circ C, V_D = 0.4 \cdot V_{RM},$ $I_{GM} = 2 \text{ A}, t_r = 0.5 \mu\text{s}$			3	μs

Triggering

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Peak forward gate voltage	V _{FGM}				12	V
Peak forward gate current	I _{FGM}				10	A
Peak reverse gate voltage	V _{RGM}				10	V
Average gate power loss	P _{G(AV)}		see Fig. 7			W

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Gate-trigger voltage	V _{GT}	T _{vj} = 25 °C			2.6	V
Gate-trigger current	I _{GT}	T _{vj} = 25 °C			400	mA
Gate non-trigger voltage	V _{GD}	V _D = 0.4 · V _{DRM} , T _{vjmax} = 125 °C			0.3	V
Gate non-trigger current	I _{GD}	V _D = 0.4 · V _{DRM} , T _{vjmax} = 125 °C			10	mA

Thermal

Maximum rated values¹⁾

Parameter	Symbol	Conditions	min	typ	max	Unit
Operating junction temperature range	T _{vj}				125	°C
Storage temperature range	T _{stg}		-40		140	°C

Characteristic values

Parameter	Symbol	Conditions	min	typ	max	Unit
Thermal resistance junction to case	R _{th(j-c)}	Double-side cooled F _m = 63... 84 kN			7	K/kW
	R _{th(j-c)A}	Anode-side cooled F _m = 63... 84 kN			14	K/kW
	R _{th(j-c)C}	Cathode-side cooled F _m = 63... 84 kN			14	K/kW
Thermal resistance case to heatsink	R _{th(c-h)}	Double-side cooled F _m = 63... 84 kN			1.5	K/kW
	R _{th(c-h)}	Single-side cooled F _m = 63... 84 kN			3	K/kW

Analytical function for transient thermal impedance:

$$Z_{th(j-c)}(t) = \sum_{i=1}^n R_i (1 - e^{-t/\tau_i})$$

i	1	2	3	4
R _i (K/kW)	4.817	1.373	0.715	0.095
τ _i (s)	0.5096	0.0529	0.0038	0.0007

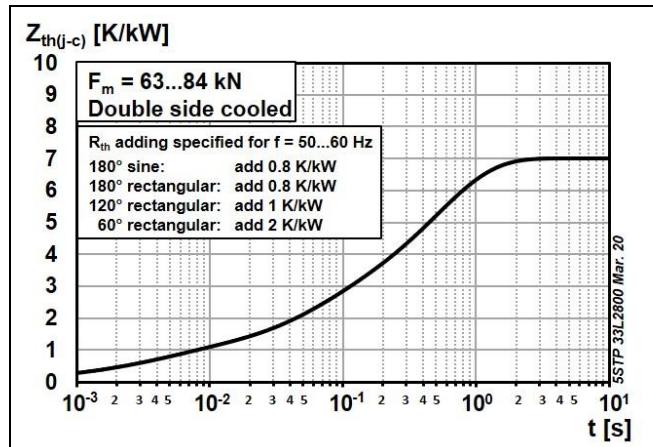
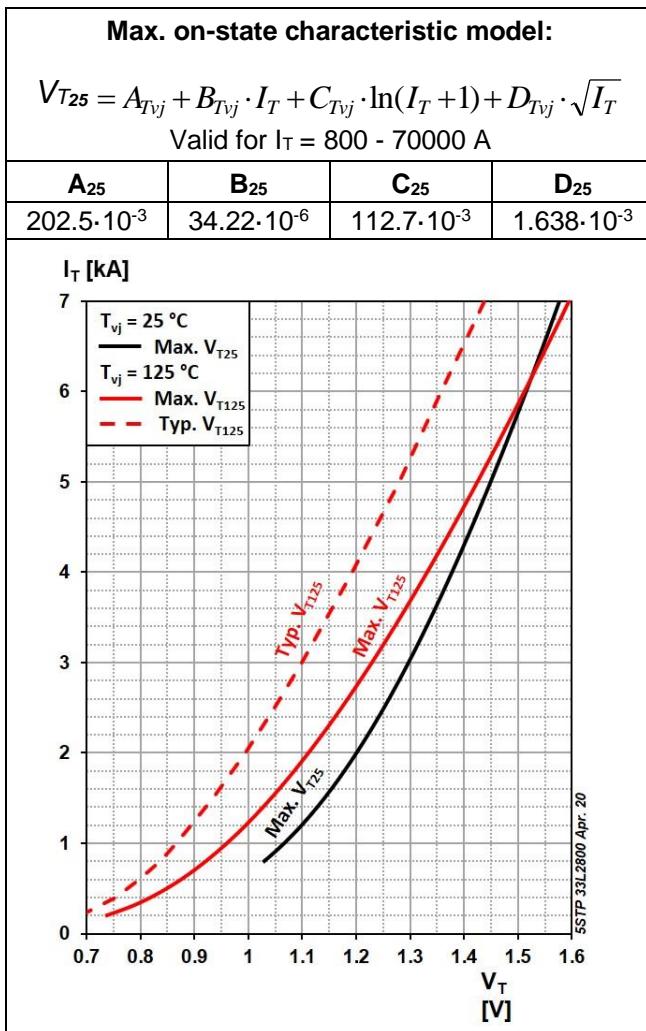
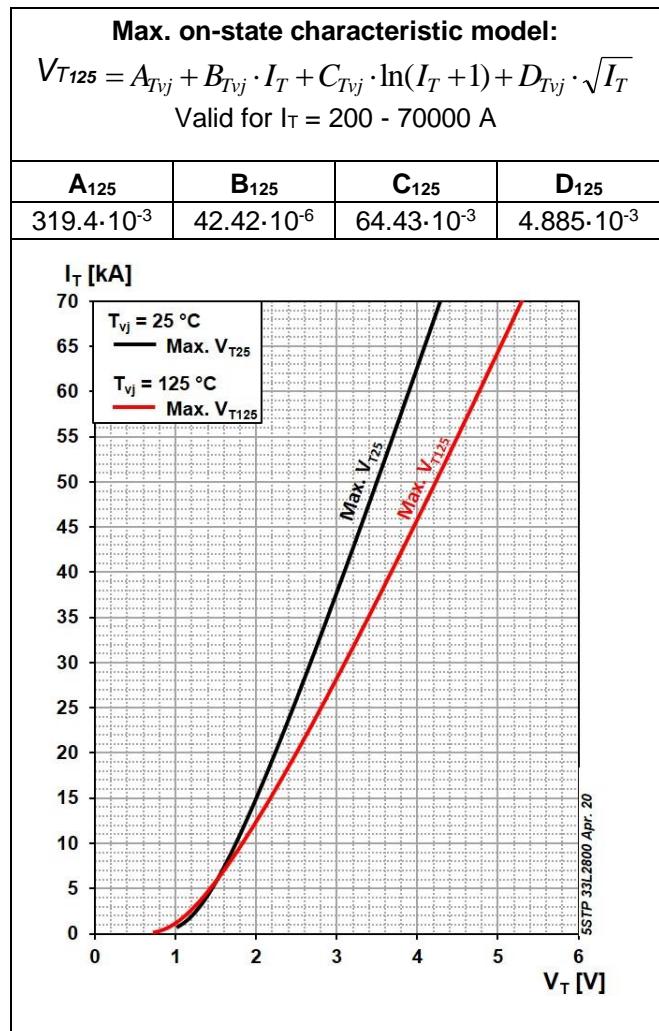
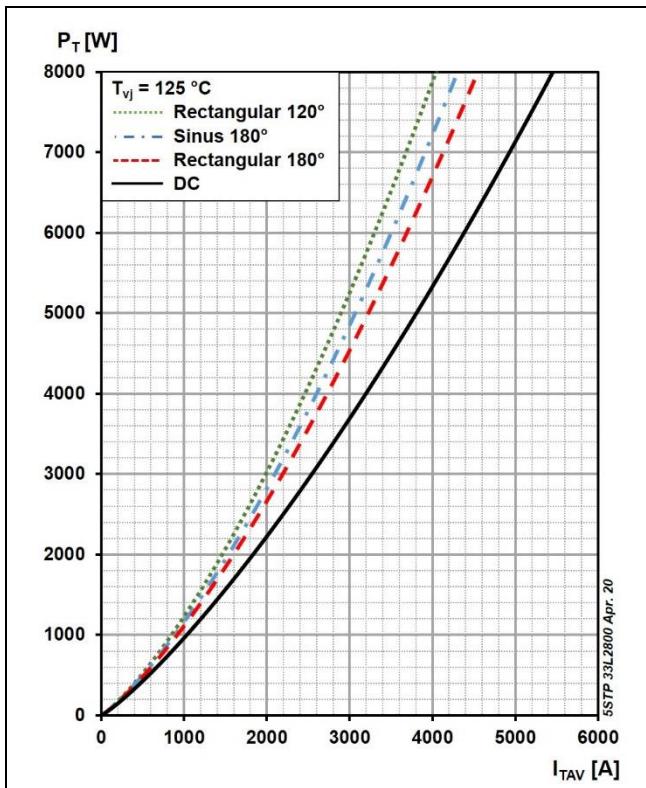
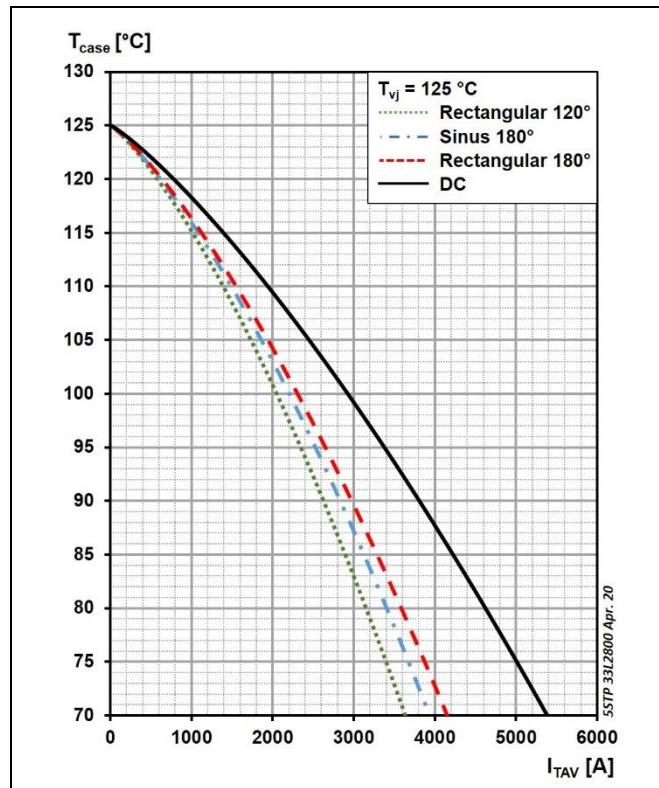
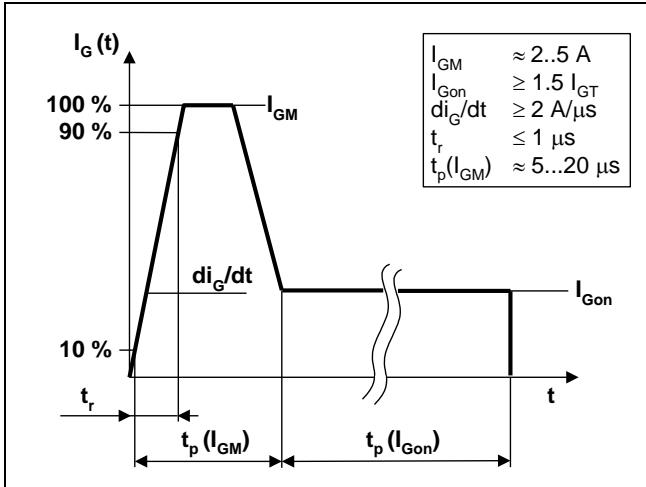
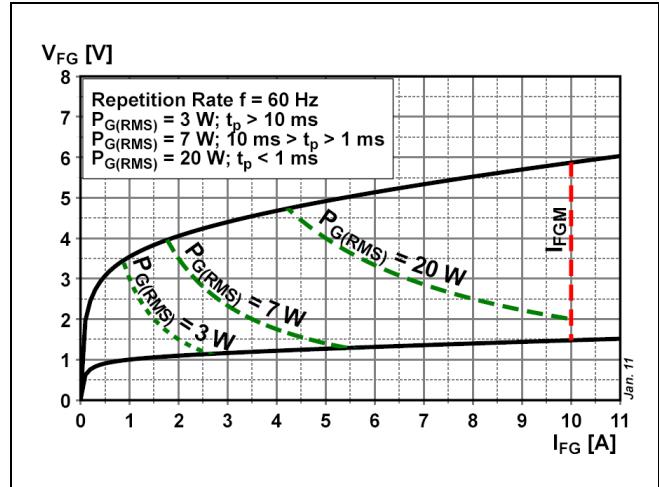
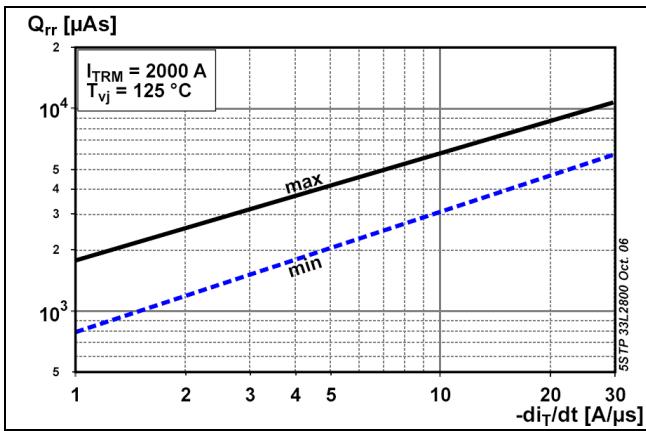
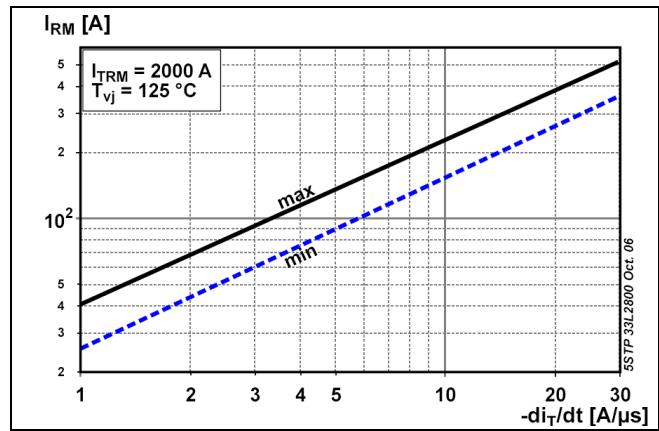


Fig. 1 Transient thermal impedance (junction-to-case) vs. time

**Fig. 2** On-state voltage characteristics**Fig. 3** On-state voltage characteristics**Fig. 4** On-state power dissipation vs. mean on-state current, turn-on losses excluded**Fig. 5** Max. permissible case temperature vs. mean on-state current, switching losses ignored

**Fig. 6** Recommended gate current waveform**Fig. 7** Max. peak gate power loss**Fig. 8** Reverse recovery charge vs. decay rate of on-state current**Fig. 9** Peak reverse recovery current vs. decay rate of on-state current

Turn-on and Turn-off losses

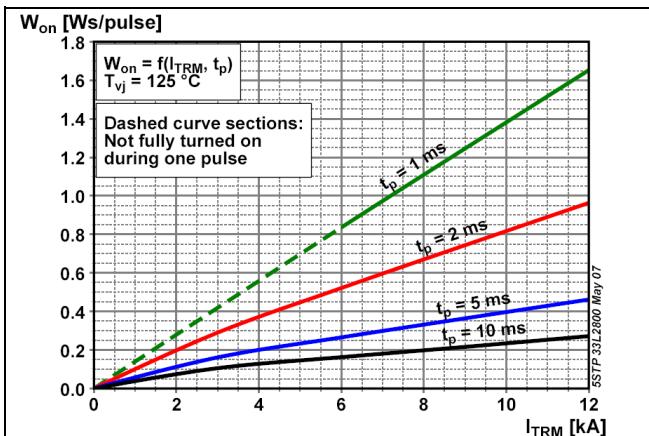


Fig. 10 Turn-on energy, half sinusoidal waves

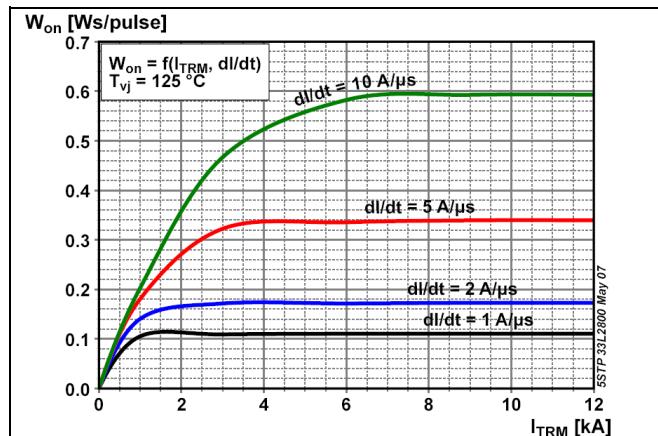


Fig. 11 Turn-on energy, rectangular waves

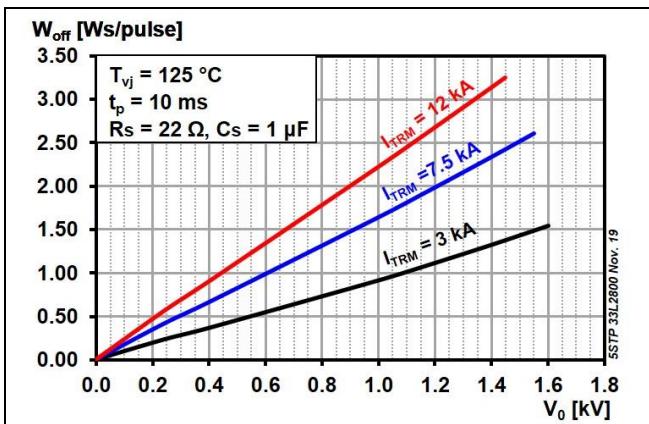


Fig. 12 Typical turn-off energy, half sinusoidal waves

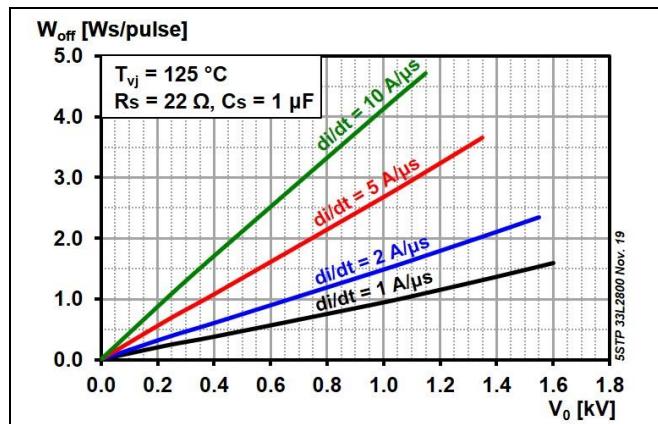


Fig. 13 Typical turn-off energy, rectangular waves

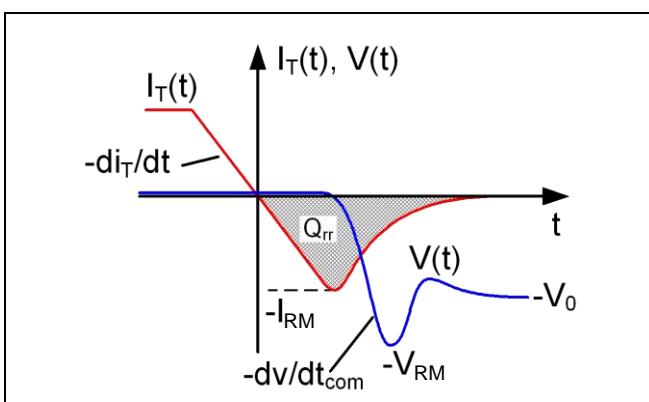


Fig. 14 Current and voltage waveforms at turn-off

Total power loss for repetitive waveforms:

$$P_{TOT} = P_T + W_{on} \cdot f + W_{off} \cdot f$$

where

$$P_T = \frac{1}{T} \int_0^T I_T \cdot V_T(I_T) dt$$

Fig. 15 Relationships for power loss

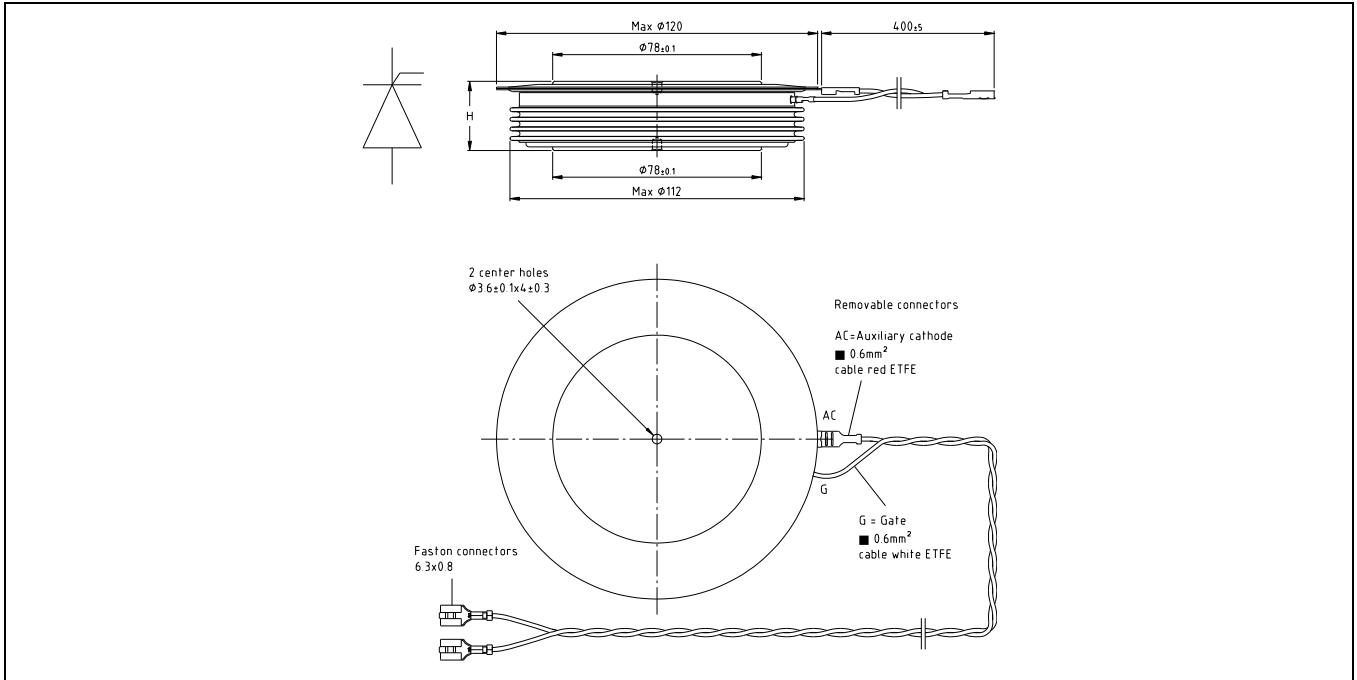


Fig. 16 Device Outline Drawing

Related documents:

- 5SYA 2020 Design of RC-Snubbers for Phase Control Applications
- 5SYA 2049 Voltage definitions for phase control and bi-directionally controlled thyristors
- 5SYA 2051 Voltage ratings of high power semiconductors
- 5SYA 2034 Gate-drive recommendations for phase control and bi-directionally controlled thyristors
- 5SYA 2036 Recommendations regarding mechanical clamping of Press-Pack High Power Semiconductors
- 5SYA 2102 Surge currents for Phase Control Thyristors
- 5SZK 9118 General Environmental Conditions for High Power Semiconductors

Please refer to <http://www.abb.com/semiconductors> for current version of documents.

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